

## Automotive-grade dual N-channel 30 V, 0.016 Ω typ., 40 A STripFET™ H5 Power MOSFET in PowerFLAT™ 5x6 double island

Datasheet - production data



**Figure 1. Internal schematic diagram**

## Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STL40DN3LLH5	30 V	0.018 Ω	40 A

- Designed for automotive application and AEC-Q101 qualified
- Low on-resistance
- High avalanche ruggedness
- Low gate drive power loss
- Wettable flank package

## Applications

- Switching applications

## Description

This device is an N-channel Power MOSFET developed using STMicroelectronics' STripFET™ H5 technology. The device has been optimized to achieve very low on-state resistance, contributing to a FoM that is among the best in its class.

**Table 1. Device summary**

Order code	Marking	Package	Packing
STL40DN3LLH5	40DN3LLH5	PowerFLAT™ 5x6 double island	Tape and reel

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	30	V
$V_{GS}$	Gate-source voltage	$\pm 22$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ C$	40	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100^\circ C$	28	A
$I_D^{(2)}$	Drain current (continuous) at $T_{pcb} = 25^\circ C$	11	A
$I_D^{(2)}$	Drain current (continuous) at $T_{pcb}=100^\circ C$	7	A
$I_{DM}^{(2)(3)}$	Drain current (pulsed)	44	A
$I_{DM}^{(1)(3)}$	Drain current (pulsed)	160	A
$P_{TOT}^{(1)}$	Total dissipation at $T_C = 25^\circ C$	50	W
$P_{TOT}^{(2)}$	Total dissipation at $T_{pcb} = 25^\circ C$	4.7	W
$T_J$	Operating junction temperature range	-55 to 175	$^\circ C$
$T_{stg}$	Storage temperature range		

1. The value is rated according  $R_{thj-c}$
2. The value is rated according  $R_{thj-pcb}$
3. Pulse width limited by safe operating area

**Table 3. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	3.0	$^\circ C/W$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	32	$^\circ C/W$

1. When mounted on FR-4 board of 1inch<sup>2</sup>, 2oz Cu, t < 10 sec

## 2 Electrical characteristics

( $T_{CASE}=25\text{ }^{\circ}\text{C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\text{ }\mu\text{A}, V_{GS} = 0\text{ V}$	30			V
$I_{DSS}$	Zero gate voltage drain current	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^{\circ}\text{C}^{(1)}$			10	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current	$V_{GS} = \pm 22\text{ V}, V_{DS} = 0\text{ V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1	1.5		V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}, I_D = 5.5\text{ A}$		0.016	0.018	$\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 5.5\text{ A}$		0.02	0.025	$\Omega$

1. Defined by design, not subject to production test

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}, V_{GS} = 0\text{ V}$	-	475	-	pF
$C_{oss}$	Output capacitance		-	97	-	pF
$C_{rss}$	Reverse transfer capacitance		-	19	-	pF
$Q_g$	Total gate charge	$V_{DD} = 15\text{ V}, I_D = 11\text{ A}$ $V_{GS} = 4.5\text{ V}$ (see <a href="#">Figure 13</a> )	-	4.5	-	nC
$Q_{gs}$	Gate-source charge		-	1.7	-	nC
$Q_{gd}$	Gate-drain charge		-	1.9	-	nC

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 15\text{ V}, I_D = 11\text{ A}, R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$ (see <a href="#">Figure 12</a> )	-	4	-	ns
$t_r$	Rise time		-	22	-	ns
$t_{d(off)}$	Turn-off delay time		-	13	-	ns
$t_f$	Fall time		-	2.8	-	ns

**Table 7. Source drain diode**

<b>Symbol</b>	<b>Parameter</b>	<b>Test conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 11 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.1	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 11 \text{ A},$ $di/dt = 100 \text{ A}/\mu\text{s},$ $V_{DD} = 25 \text{ V}, T_j = 150^\circ\text{C}$	-	16.2		ns
$Q_{rr}$	Reverse recovery charge		-	1		nC
$I_{RRM}$	Reverse recovery current		-	8.1		A

1. Pulsed: pulse duration=300μs, duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

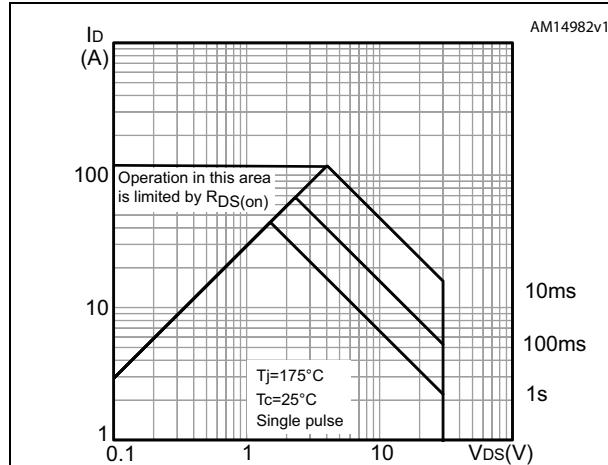


Figure 3. Thermal impedance

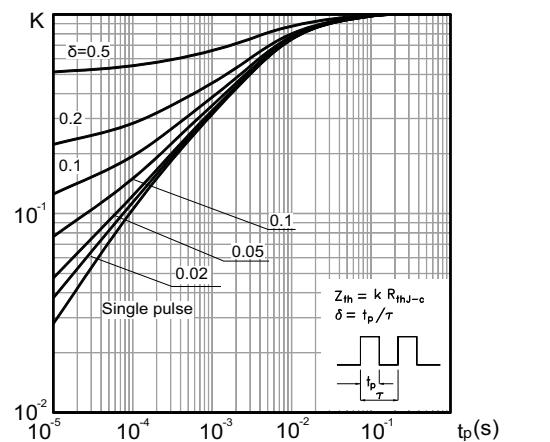


Figure 4. Output characteristics

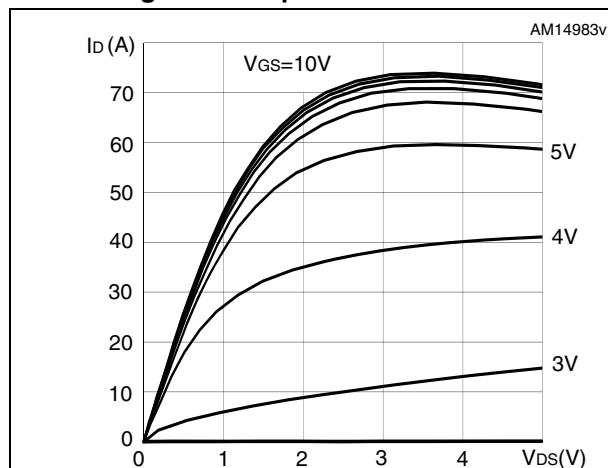


Figure 5. Transfer characteristics

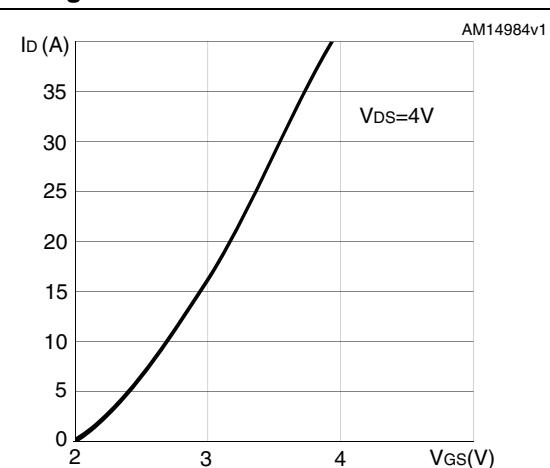
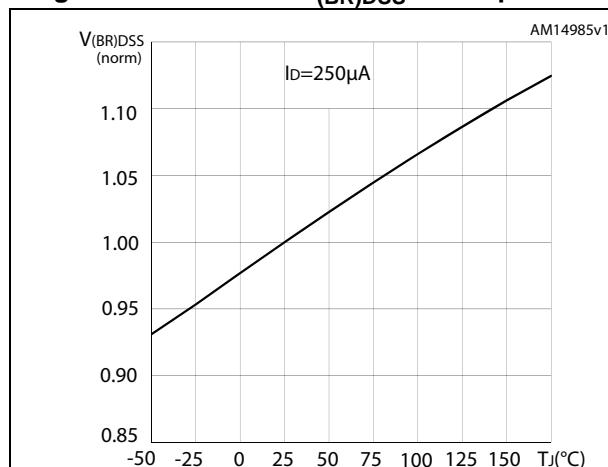
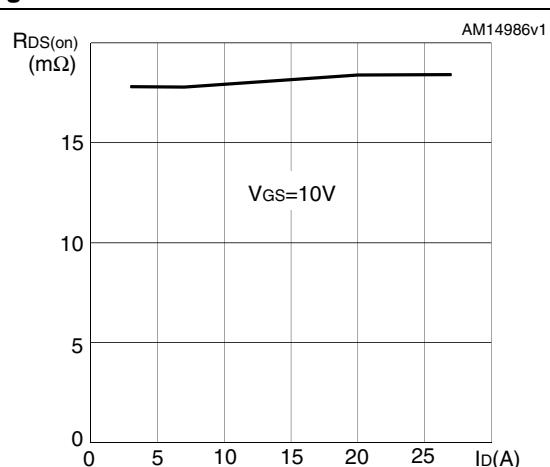
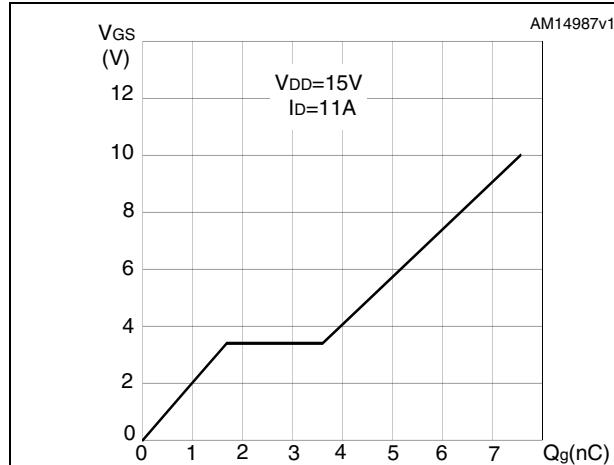
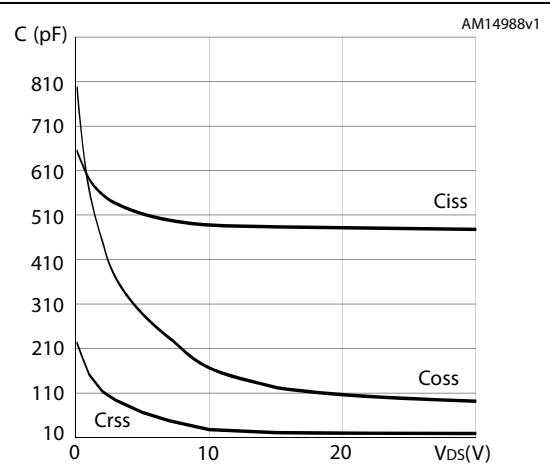
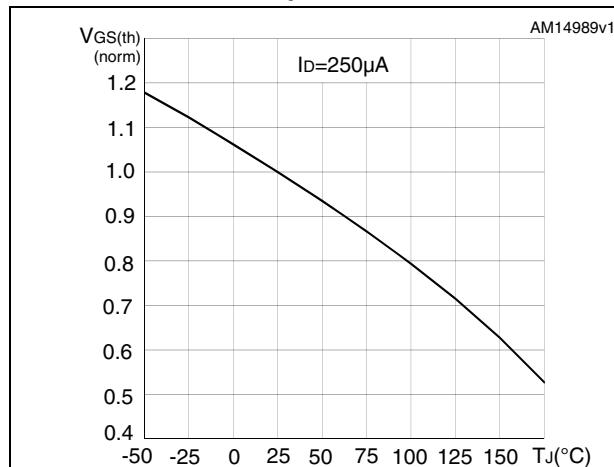
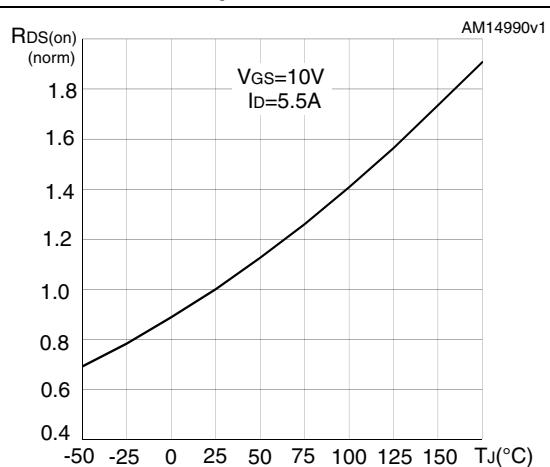
Figure 6. Normalized  $V_{(BR)DSS}$  vs temperature

Figure 7. Static drain-source on-resistance



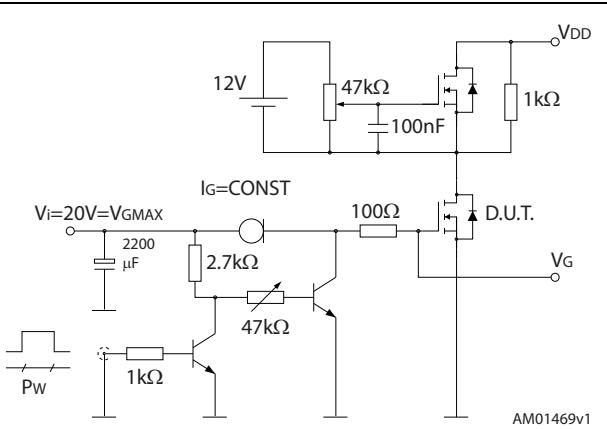
**Figure 8. Gate charge vs gate-source voltage****Figure 9. Capacitance variations****Figure 10. Normalized gate threshold voltage vs temperature****Figure 11. Normalized on-resistance vs temperature**

### 3 Test circuits

**Figure 12. Switching times test circuit for resistive load**



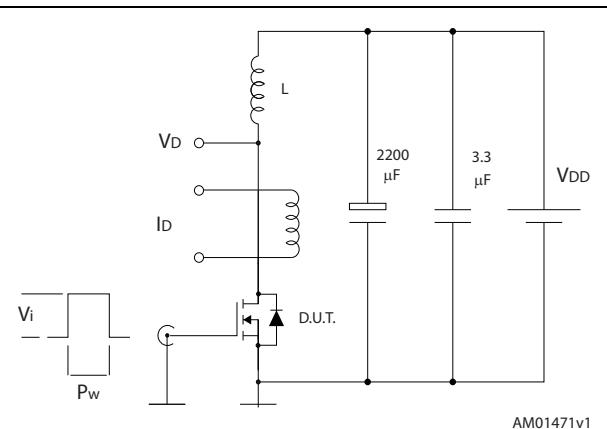
**Figure 13. Gate charge test circuit**



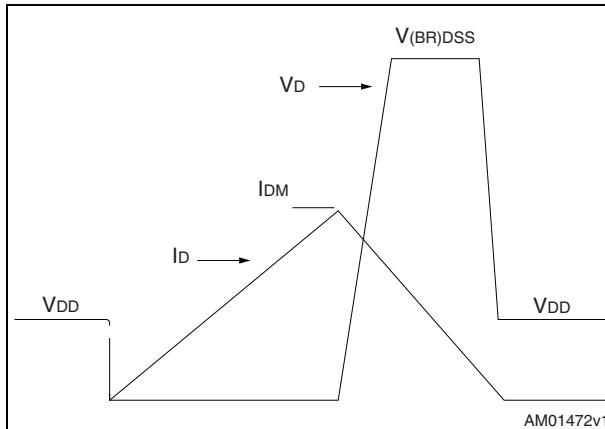
**Figure 14. Test circuit for inductive load switching and diode recovery times**



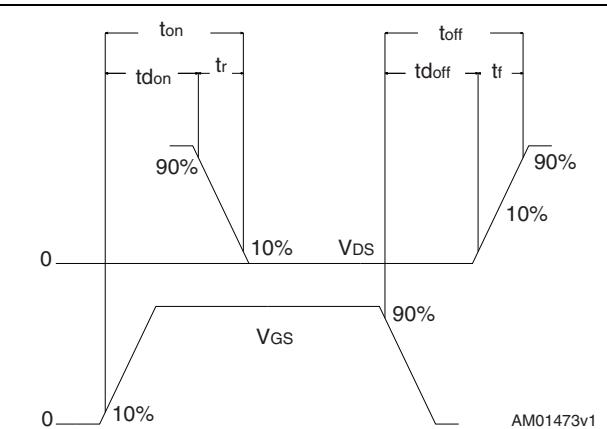
**Figure 15. Unclamped inductive load test circuit**



**Figure 16. Unclamped inductive waveform**



**Figure 17. Switching time waveform**

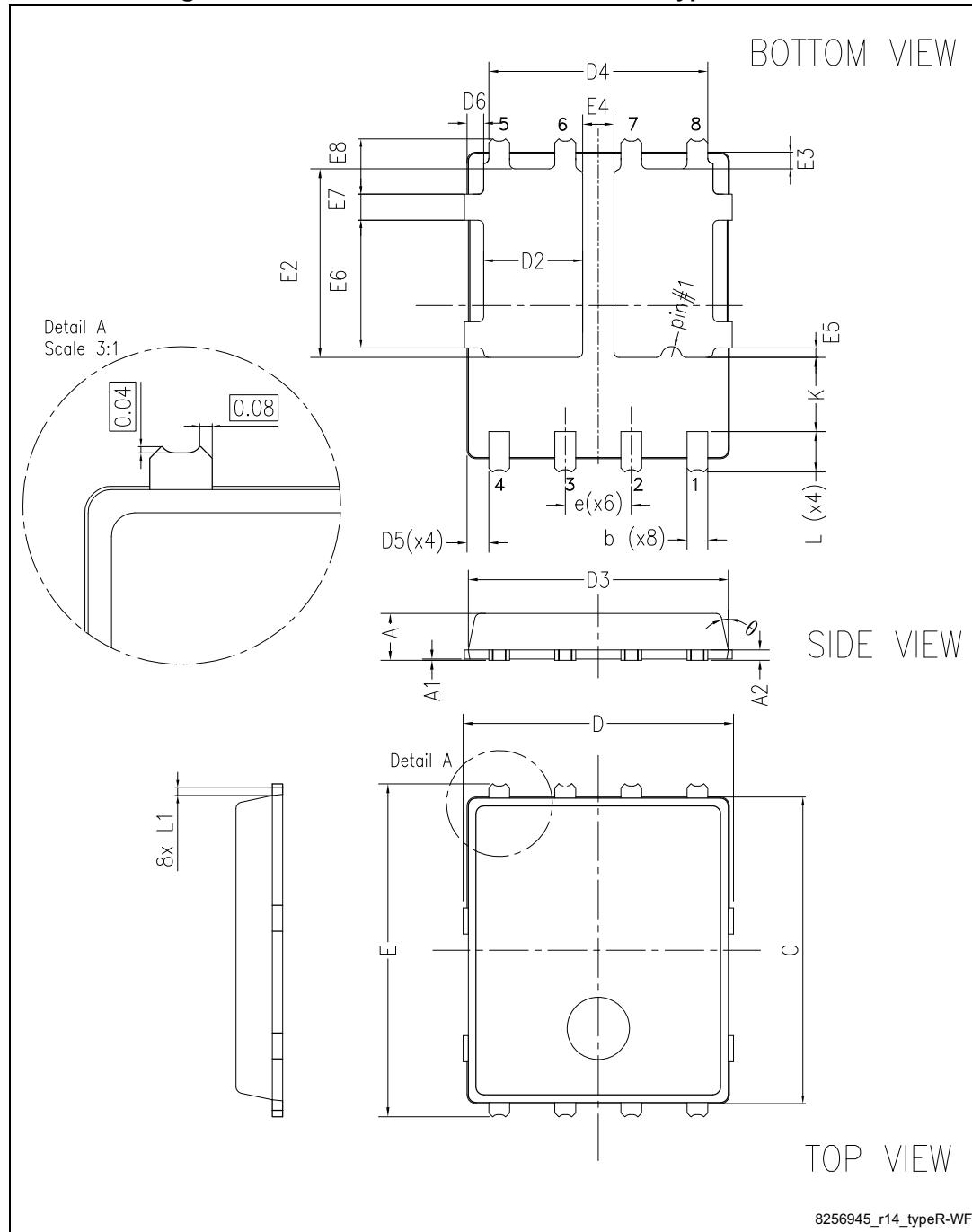


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK® is an ST trademark.

## 4.1 PowerFLAT 5x6 double island WF type R

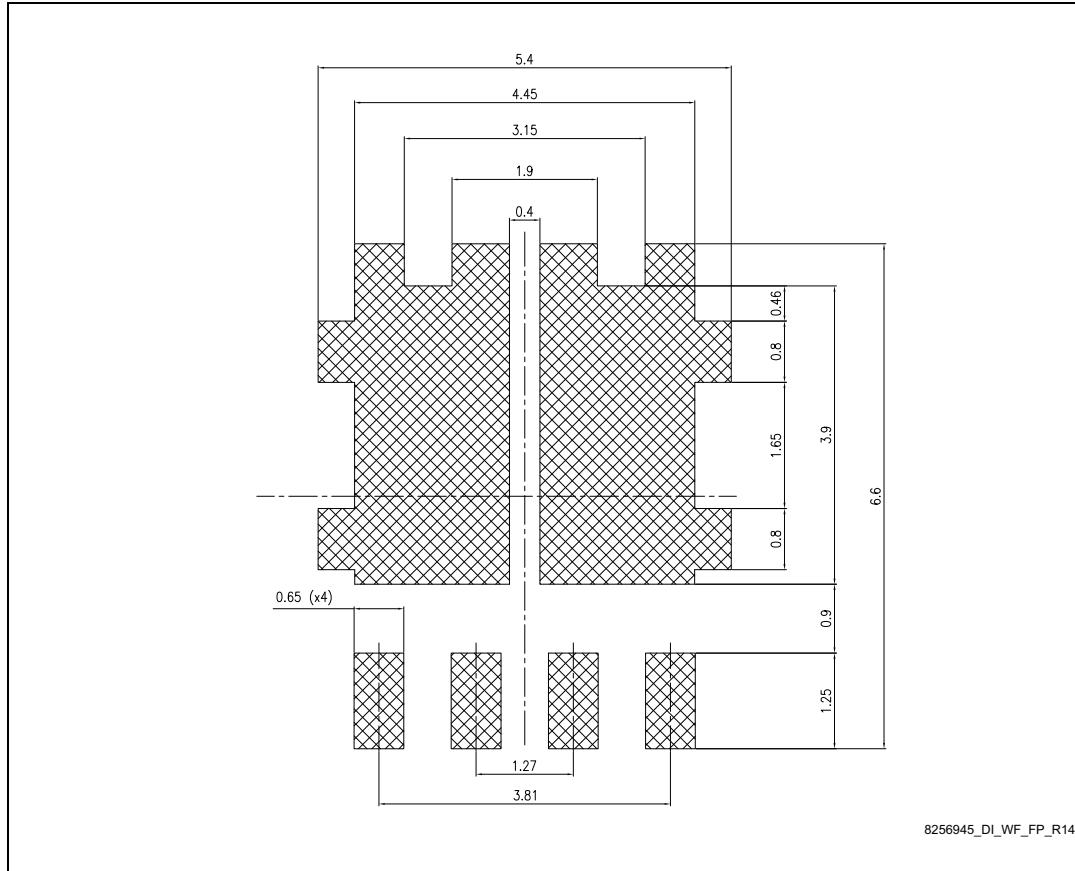
Figure 18. PowerFLAT 5x6 double island WF type R outline



**Table 8. PowerFLAT 5x6 double island WF type R mechanical data**

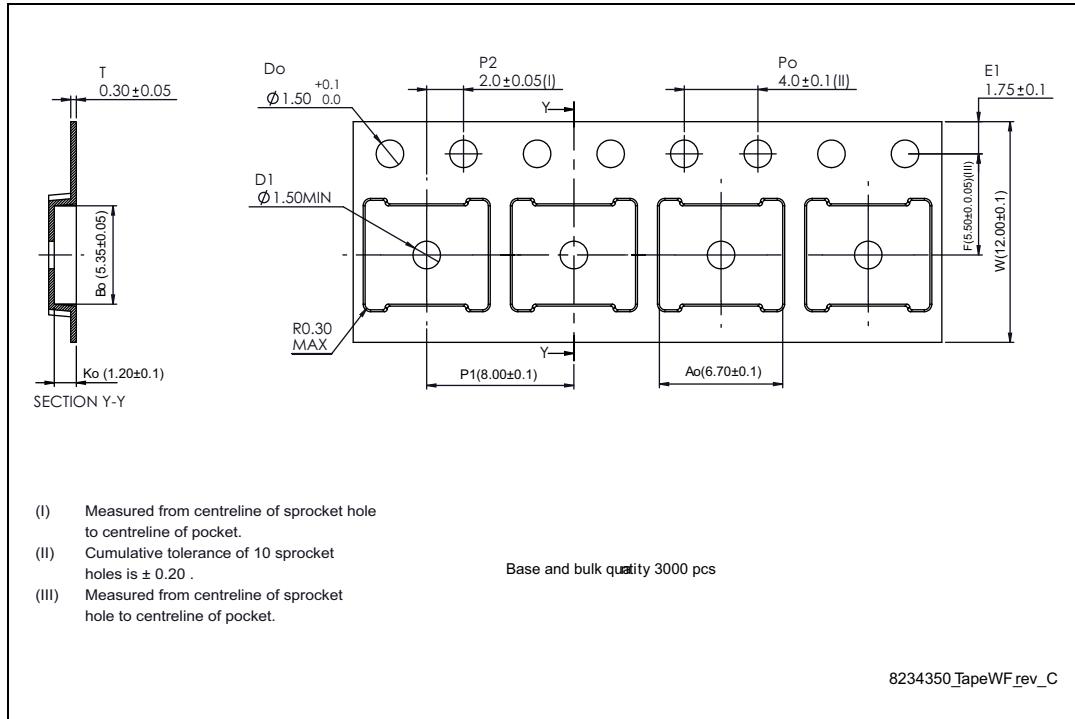
Ref.	Dimensions (mm)		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.80	6.00	6.20
D	5.00	5.20	5.40
D2	1.68		1.88
D3	4.80	5.00	5.20
D4	4.05	4.20	4.35
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
e		1.27	
E	6.20	6.40	6.60
E2	3.50		3.70
E4	0.55		0.75
E6	2.35		2.55
E7	0.40		0.60
K	1.275		1.575
L	0.70		0.90
L1		0.275	
θ	0°		12°

**Figure 19. PowerFLAT™ 5x6 double island recommended footprint  
(dimensions are in mm)**

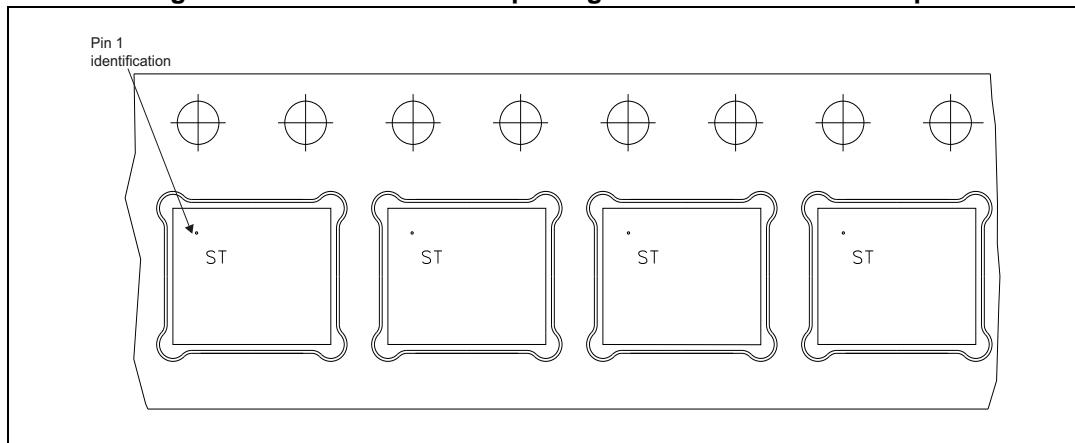


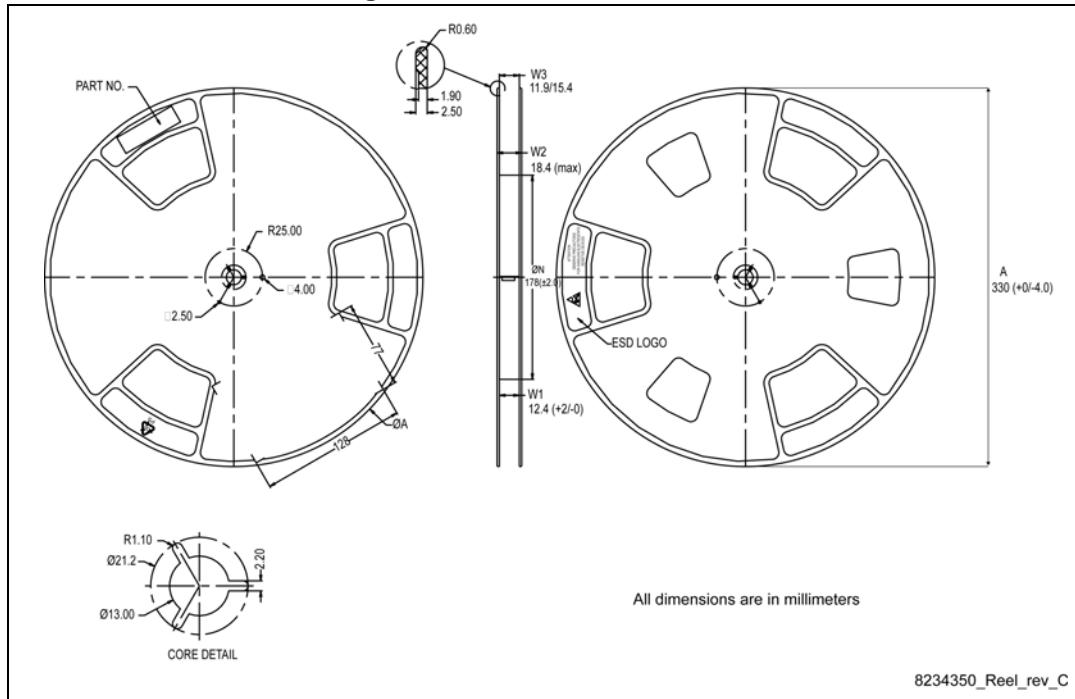
## 5 Packing information

**Figure 20. PowerFLAT™ 5x6 WF tape**



**Figure 21. PowerFLAT™ 5x6 package orientation in carrier tape**



**Figure 22. PowerFLAT™ 5x6 reel**

## 6 Revision history

Table 9. Document revision history

Date	Revision	Changes
24-Jan-2011	1	First release.
03-Oct-2012	2	Section 2.1: Electrical characteristics (curves) has been added. Document status promoted from preliminary data to datasheet. Minor text changes.
14-Dec-2012	3	Modified the Applications section on the coverpage to "Automotive switching applications".
23-Feb-2015	4	Updated Section 4: Package mechanical data and added Section 5: Packing information. Updated title and features in cover page. Minor text changes.
27-Oct-2015	5	Updated title and features in cover page. Updated Table 2, Table 3, Table 4 and Table 7. Updated Section 4: Package information Minor text changes.
11-Mar-2016	6	Updated silhouette in cover page. Updated <a href="#">Table 1: Device summary</a> , <a href="#">Table 2: Absolute maximum ratings</a> , <a href="#">Table 3: Thermal resistance</a> and <a href="#">Table 4: On/off states</a> . Updated <a href="#">Figure 2: Safe operating area</a> . Updated <a href="#">Section 4.1: PowerFLAT 5x6 double island WF type R</a> Updated <a href="#">Section 5: Packing information</a> . Minor text changes.

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